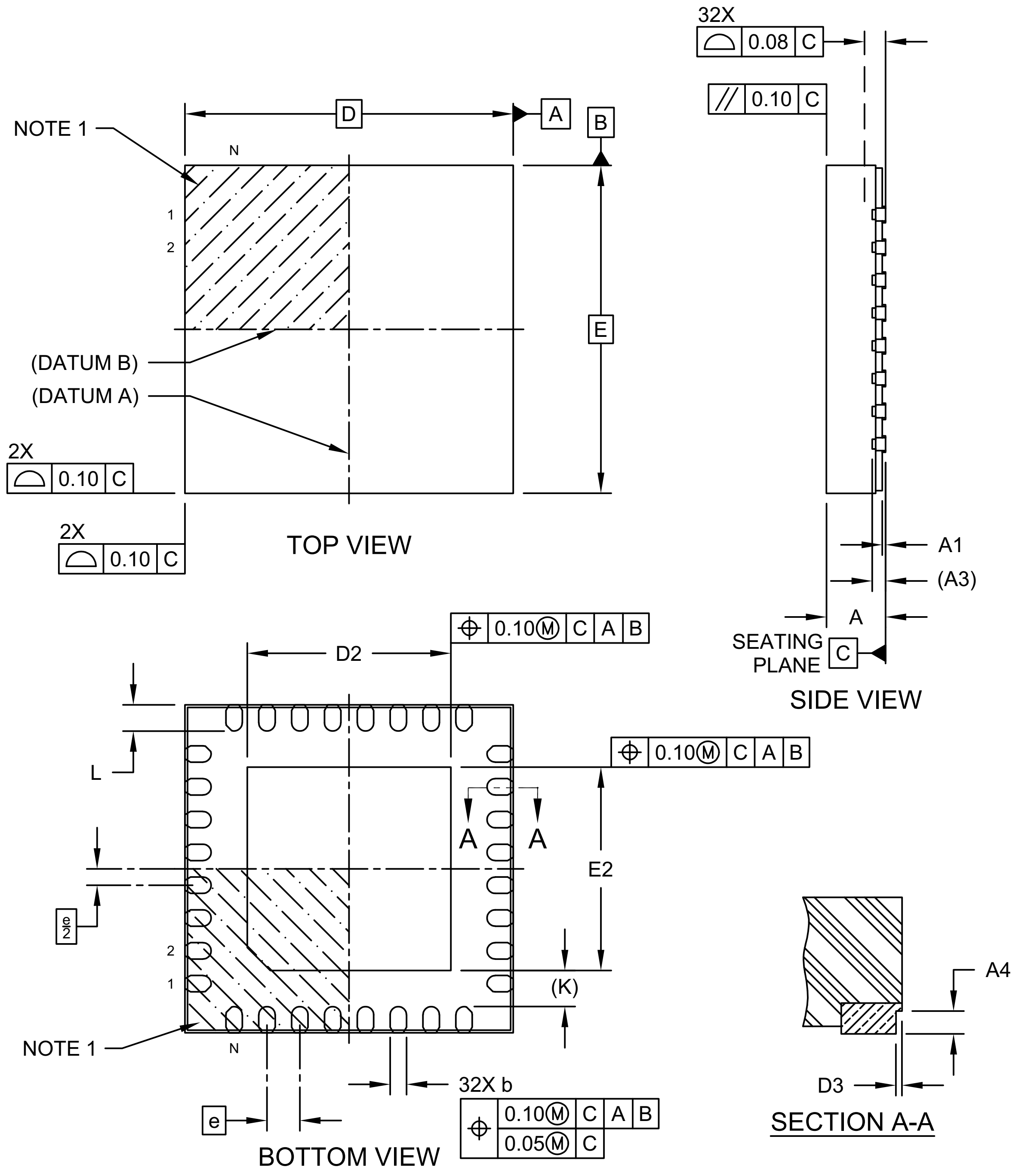
32-Lead Very Thin Plastic Quad Flat, No Lead Package (PRA) - 5x5 mm Body [VQFN] With 3.1 mm Exposed Pad and Stepped Wettable Flanks

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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32-Lead Very Thin Plastic Quad Flat, No Lead Package (PRA) - 5x5 mm Body [VQFN] With 3.1 mm Exposed Pad and Stepped Wettable Flanks

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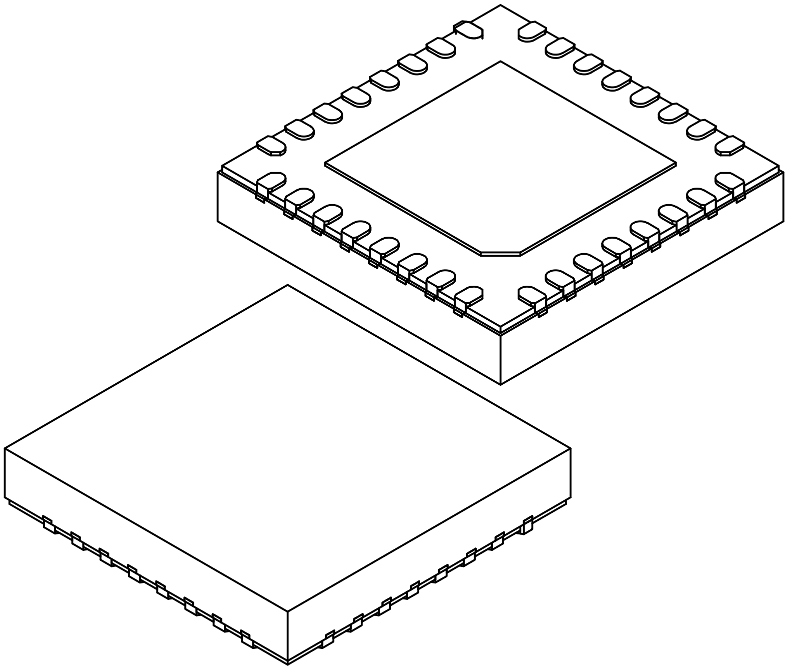

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		32	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.85	0.90
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.203 REF	
Overall Length	D		5.00 BSC	
Exposed Pad Length	D2	3.00	3.10	3.20
Overall Width	E		5.00 BSC	
Exposed Pad Width	E2	3.00	3.10	3.20
Terminal Width	b	0.20	0.25	0.30
Terminal Length	L	0.35	0.40	0.45
Terminal-to-Exposed-Pad	K		0.55 REF	
Step Height	A4	0.10	0.125	0.15
Step Length	D3	-	-	0.04

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M
    BSC: Basic Dimension. Theoretically exact value shown without tolerances.
    REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1268 Rev B Sheet 2 of 2

32-Lead Very Thin Plastic Quad Flat, No Lead Package (PRA) - 5x5 mm Body [VQFN] With 3.1 mm Exposed Pad and Stepped Wettable Flanks

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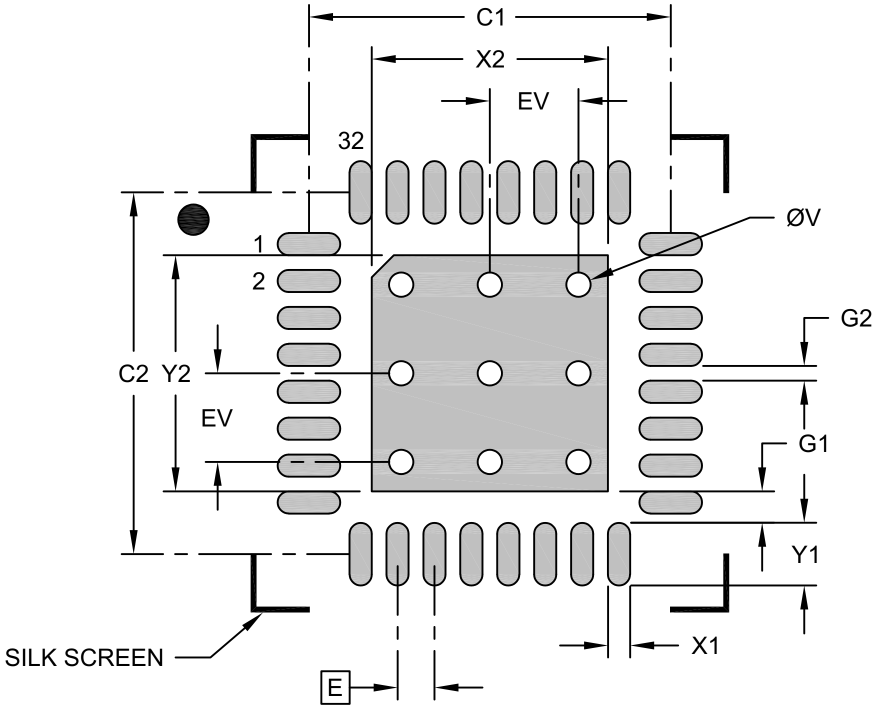

RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	X2			3.20
Optional Center Pad Length	Y2			3.20
Contact Pad Spacing	C1		4.90	
Contact Pad Spacing	C2		4.90	
Contact Pad Width (X32)	X1			0.30
Contact Pad Length (X32)	Y1			0.85
Contact Pad to Center Pad (X32)	G1	0.43		
Contact Pad to Center Pad (X28)	G2	0.20		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

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